

HSPF

TECHNICAL SPECS:

Current Rating: 2.0AMP
 Withstand Voltage: 500V AC/Minute
 Contact Resistance: 30mΩ Max
 Insulation Resistance: 1000MΩ Min
 Operation Temperature: -40°C to +105°C

Contact Material: Phosphor Bronze, Nut: Brass
 Contact plating: Au or Sn over Ni
 Insulator Material: LCP/PA6T+30%G.F UL94V-0

Ordering Information

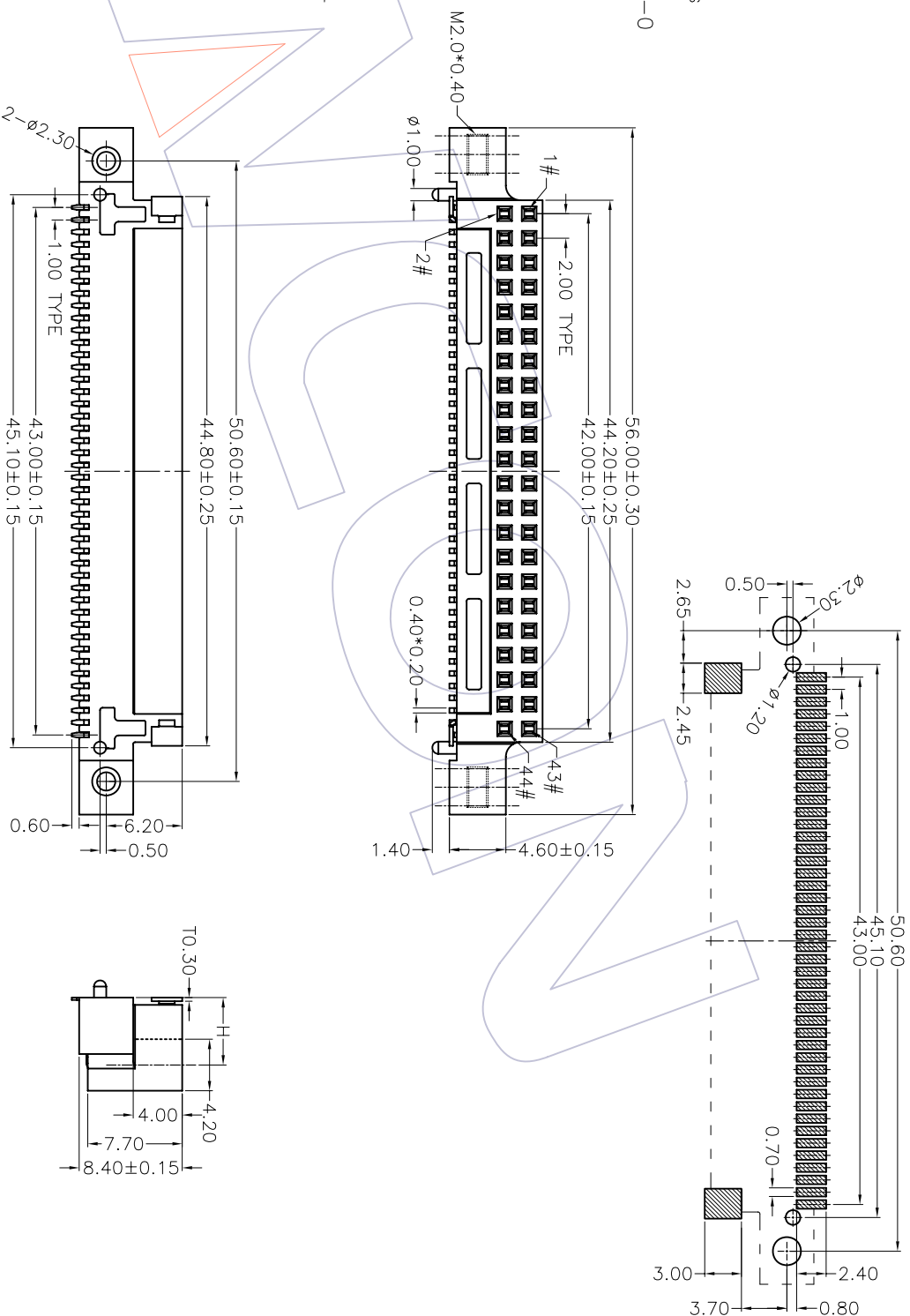
22A-XXX 44 M XX XN X1

The Distance of Connector center to the P.C.B
 049:H=4.90mm
 055:H=5.50mm
 063:H=6.30mm

Contact Plating
 G0=Gold Flash
 G1=3u"Gold
 G2=5u"Gold
 G3=10u"Gold
 G4=15u"Gold
 G5=30u"Gold

Insulator Material
 A=Triay
 T=Tube
 C=PA6T
 D=LCP

Packaging
 S0=Gold Flash/Tin
 S1=3u"Gold/Tin
 S2=5u"Gold/Tin
 S3=10u"Gold/Tin
 S4=15u"Gold/Tin
 S5=30u"Gold/Tin
 SN=Tin



Recommended P.C.B Layout(Top Side)
 (PCB BOARD TOLERANCE±0.05)

OPERATION	±0.40	DRAW	WEIXD	09/01/03	SCALE	1:1	 WCON 维峰五金电子有限公司 WAFER HARDWARE ELECTRONICS CO.,LTD
DESIGN	±0.25	CHECK			UNIT	mm	
CHECK	±0.15	APPROVE			SIZE	A4	PART NO.
ANGLE	± 3'				SHEET	1/1	TITLE:
DIM	TOL				PROJ.		Customer NO.

REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE	5	6	7	8	9	10
A0	09/01/03	NEW								